

Title (en)
Interconnection structure including blind via holes intended for being metallised

Title (de)
Verbindungsstruktur, die Sacklöcher umfasst, die metallisiert werden sollen

Title (fr)
Structure d'interconnexion comprenant des vias borgnes destinés à être métallisés

Publication
EP 2365743 B1 20170719 (FR)

Application
EP 11157130 A 20110307

Priority
FR 1051727 A 20100310

Abstract (en)
[origin: EP2365743A2] The structure (100) has a substrate (102) whose face (110) is integrated to a face (111) of another substrate (104). An electric contact (114) is arranged against the face of the latter substrate and next to a blind via (108) and/or against the face and/or another face (112) of the former substrate. A channel (116) provides communication of the via with an environment outside of the structure and/or with a cavity formed in the structure. The channel extends parallel to one of the faces of the substrates. An independent claim is also included for a method for realization of an interconnection structure.

IPC 8 full level
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